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Application Data	Attomey Dock		er	81872.0124					
• •			Application Number			Not assigned			
Title of Invention Mold, Method of Forming the Same, and Method of Producing Polycrystalline Silicon Substrate Using the Mold									
The application data sheet is part of the provisional or nonprovisional application for which it is being submitted. The following form contains the bibliographic data arranged in a format specified by the United States Patent and Trademark Office as outlined in 37 CFR 1.76 This document may be completed electronically and submitted to the Office in electronic format using the Electronic Filing System (EFS) or the document may be printed and included in a paper filed application.									
Secrecy Order 37	CFR 5.2								
Portions or all of the application associated with this Application Data Sheet may fall under a Secrecy Order pursuant to 37 CFR 5.2 (Paper filers only. Applications that fall under Secrecy Order may not be filed electronically.)									
Applicant Information:									
Applicant 1									
Applicant Authori	ty 🖾	Legal Representative	under 35 U.S.C. 117	-	arty of Interest unde	r 35 U.S.C. 118			
Prefix Given I	lame	Middle Name	us . sateles		Fam	illy Name	Suffix		
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Residence Inform	ation (Sele	ect One) US Resid	ency Non US R	Residency		Active US Military	Service		
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Citizenship under 37 CFR 1.41(b) Japan									
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All Inventors Must Be Listed – Additional Inventor Information blocks are contained on the attached sheet.									
Correspondence Information:									
Enter either Customer Number or complete the Correspondence Information section below. For further information see 37 CFR 1.33(a).									
An Address is being provided for the correspondence information of this application.									
Customer Number 26021									
Email Address ljmcdure@hhlaw.com									
Application Information:									
Title of the Invent	rming the Sam con Substrate U	ne, and M Using the	letho Mo	od of Produci ld	ng				
Attorney Docket Number		Small Entity Status Claimed							
Application Type	l	Jtil <b>i</b> ty							
Subject Matter									
Suggested Class	(if any)			Sub Clas	ss (if	fany)			
Suggested Technology Center (if any)									
Total Number of E	rawing Si	neets (if any)   14	Sugges	ted Figure fo	r Publ	ication (if any)			
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		Attorney Docket Number	872.0124					
Application Data	Sneet 3	/ CFR 1./6	Application Number	Not	ot assigned			
Title of Invention		Method of Forming Substrate Using th	the Same, and Method of Proc					line
Publication Inform	nation:	4	·············					
Request Ea	rly Public	cation (Fee required	d at time of Request 37 CFR 1	.219)				
and certify that	t the inven	tion disclosed in the at	the attached application not be publis tached application has not been and multilateral agreement, that requires	will not	be t	the sub	jec	t of an
Representative In	formatio	on:						
information in the Applica	ation Data S umber or co	Sheet does not constitute a implete the Representative	mers having a power of attorney in the ap a power of attorney in the application (se re Name section below. If both sections g processing.	e 37 CF	R 1.:	32).		
Please Select One	: 🛛 c	ıstomer Number	US Patent Practitioner	JS Repr	esen	tative (3	37 C	FR 11.9)
Customer Number	2602	21						
Domestic Priority	Informa	ntion:						
This section allows f	or the ap	olicant to claim benef	fit under 35 U.S.C. 119(e), 120, 1	21, or 3	365(	(c). Pr	ΌV	iding
this Information in the	e applicat	tion data sheet const r CFR 1 78(a)(4), and	itutes the specific reference requi d need not otherwise be made pa	red by	35 l e sr	U.S.C. pecifica	. 11 atic	19(e) or on.
Prior Application S		<u> </u>						
Application Number		Conti⊓uity Type	Prior Application Number				<u> </u>	MM-DD)
This application		Vational Phase	PCT/JP2005/001545	2005	-01	27		
				-				
Foreign Priority Ir	nformati	on:						
application for which the claim for priority	priority is as require	not claimed. Provided by 35 U.S.C. 119(	fit of foreign priority and to identify ling this information in the applica (b) and 37 CFR 1.55(a).	tion da	ıta s	sheet o	on	
Application Number		Country	Parent Filing Date (YYYY-MN	/I-DD)	_	Priority		
2004-21174		apan	2004-01-29					No
2004-96814	J	apan	2004-03-29		$\boxtimes$	Yes	L	No
					느	Yes	<u> </u>	No
	1					Yes		No

Application Data	Shoot 27 CED 1 76	Attorney Docket Number	81872.0124				
Application Data Sheet 37 CFR 1.76		Application Number	Not assigned				
Title of Invention	Mold, Method of Forming the Same, and Method of Producing Polycrystalline Silicon Substrate Using the Mold						

Assignee Information:

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the applicant or representative is require	ed in accordance with 37 CFR 1.33 and 1	0.18. Please
.4(d) for the form of the signature.		
	Date (YYYY-MM-DD)	2006-07-27
		44,228
	.4(d) for the form of the signature.	Laured Welley (YYY-MM-DD)

This collection of information is required by 37 CFR 1.76. The Information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 23 minutes to complete, including gathering, preparing, and submitting the completed application data sheet form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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Application Data Sheet 37 CFR 1.76				Attorney Docket Number			81872.0124						
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Title of Inv	Title of Invention Mold, Method of Forming the Same, and Method of Producing Polycrystalline Silicon Substrate Using the Mold												
Additiona	lagA I	icant Informa	tion:										
Applicant	2												
Applicant Authority Inventor Legal Representative under 35 U.S.C. 117 Party of Interest under 35 U.S.C. 118													
Prefix		n Name		le Name		Fan				ily Name	Suffix		
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		er 37 CFR 1.4			Japan								
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Applicant 3													
Applicant Authority Inventor Legal Representative under 35 U.S.C. 117 Party of Interest under 35 U.S.C. 118													
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Citizenship under 37 CFR 1.41(b)  Mailing Address of Applicant(s):													
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Applicant													
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Residence Information (Select One) US Residency Non US Residency Active US Military Service													
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		s of Applicant	:(s):										
Address 1													
Address 2	<u>.                                      </u>			. (D · ·									
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